

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	(10/604650).CCLS	US-PGPU B; USPAT; EPO; JPO	OR	OFF	2004/12/06 06:43
L2	1	10/604650	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 14:30
L3	0	((solder near4 mask\$3) (mask\$3 with (epoxy near3 resin 'bt' bismale\$10))) with dielectric	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:38
L4	0	(solder near4 mask\$3) with dielectric	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:10
L5	659	(solder near4 mask\$3) with packag\$3	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:11
L6	0	5 and ((solder near4 mask\$3) with dielectric)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:11
L7	150	5 and ((solder near4 mask\$3) with (epoxy resin 'bt' bismaleimide adj triazine))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:13
L8	0	7 and ((dielectric) with (epoxy resin 'bt' bismaleimide adj triazine))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:13
L9	19	7 and ((dielectric) with (epoxy resin 'bt' bismaleimide adj triazine))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:22
L10	5	9 and ((dielectric mask\$) with (thermal\$5 coefficient\$3 expansion\$4))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:16
L11	11	9 and (temperature degree)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:23
L12	166	(solder near4 mask\$3) with (epoxy near3 resin 'bt' bismale\$10).	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:04
L13	3421	(dielectric) with (epoxy near3 resin 'bt' bismale\$10)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:06

L14	15927	(dielectric insulat\$3) with (epoxy near3 resin 'bt' bismale\$10)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:39
L15	662	(solder near4 mask\$3) with dielectric	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:03
L16	13	((solder near4 mask\$3) with dielectric) with (epoxy near3 resin 'bt' bismale\$10)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:57
L17	3421	13 and 13	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:59
L18	240	17 and ( solder with (expans\$4 coefficient thermal\$3))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:00
L19	19	12 and 13	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 07:59
L20	119	18 and ( dielectric with (expans\$4 coefficient thermal\$3))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 12:23
L21	101	20 and packag\$3	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:00
L22	618	(solder adj mask\$3) with dielectric	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:07
L23	25	22 and (solder ) with (epoxy near3 resin 'bt' bismale\$10)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:05
L24	25	22 and (solder ) with (epoxy near3 resin 'bt' bismale\$10)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:05
L25	3428	23 (dielectric) with (epoxy near3 resin 'bt' bismale\$10)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:05
L26	18	23 and (dielectric) with (epoxy near3 resin 'bt' bismale\$10)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:06
L27	701	(solder adj mask\$3 soldermask\$3) with dielectric	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:13



L28	158	27 and (solder adj mask\$3 soldermask\$3) with (epoxy resin 'bt' bismaleimide adj triazine)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:08
L29	131	28 and (epoxy resin 'bt' bismaleimide adj triazine) with dielectric	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 08:11
L30	131	29 and (epoxy resin 'bt' bismaleimide adj triazine dielectric solder adj mask\$3 soldermask\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 14:36
L31	38	30 and (expans\$4 coefficient thermal\$3) with (solder adj mask\$3 soldermask\$3 dielectric)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 09:49
L32	0	10/8108049	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 09:50
L33	1	10/808049	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 09:56
L34	0	10/698258	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 09:56
L35	701	27 and (dielectric expans\$4 coefficient thermal\$3 soldermask solder dj mask)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 12:25
L36	701	35 and (dielectric with (expans\$4 coefficient thermal\$3 soldermask solder dj mask))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 12:25
L37	701	35 and ((dielectric expans\$4 coefficient thermal\$3) with (soldermask solder dj mask))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 12:26
L38	701	36 and ((dielectric expans\$4 coefficient thermal\$3) with (soldermask solder dj mask))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 12:26
L39	701	38 and ((dielectric expans\$4 coefficient thermal\$3 soldermask solder dj mask))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 12:27
L40	174	38 and ( expans\$4 near4 coefficient )	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 12:27

L41	6	"5665526"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 14:30
L42	2	10/688354	US-PGPU B; USPAT; EPO; JPO	OR	ON	2004/12/06 14:36